

# SOT2151-1

LFBGA169, low profile fine-pitch ball grid array package, 169 terminals, 0.8 mm pitch, 11 mm x 11 mm x 1.37 mm body

26 July 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA169
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	23-06-2021
<b>Manufacturer package code</b>	98ASA01811D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.85	11	11.15	mm
package width	10.85	11	11.15	mm
package height	-	1.37	1.52	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	169	-	



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2 Package outline

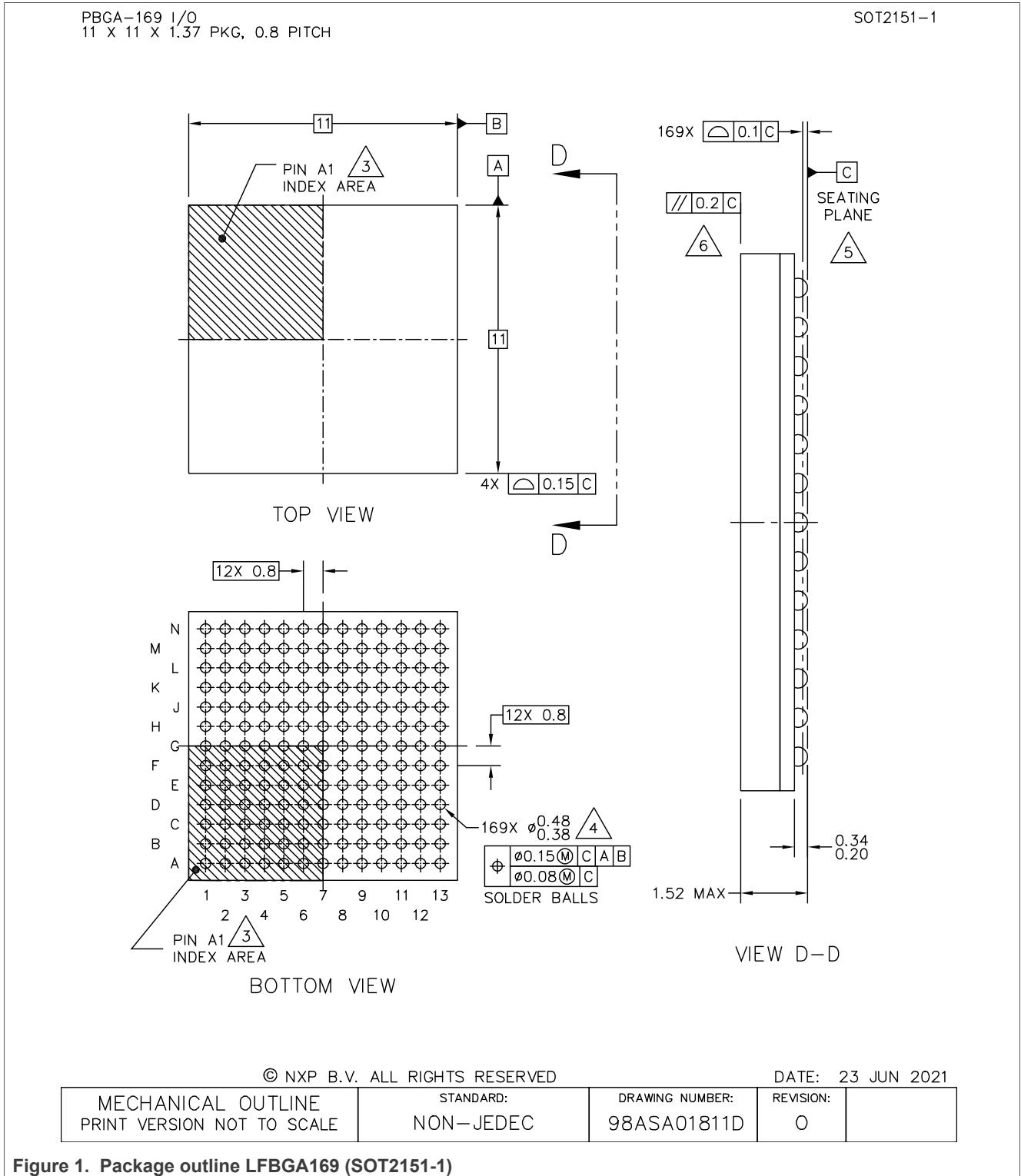
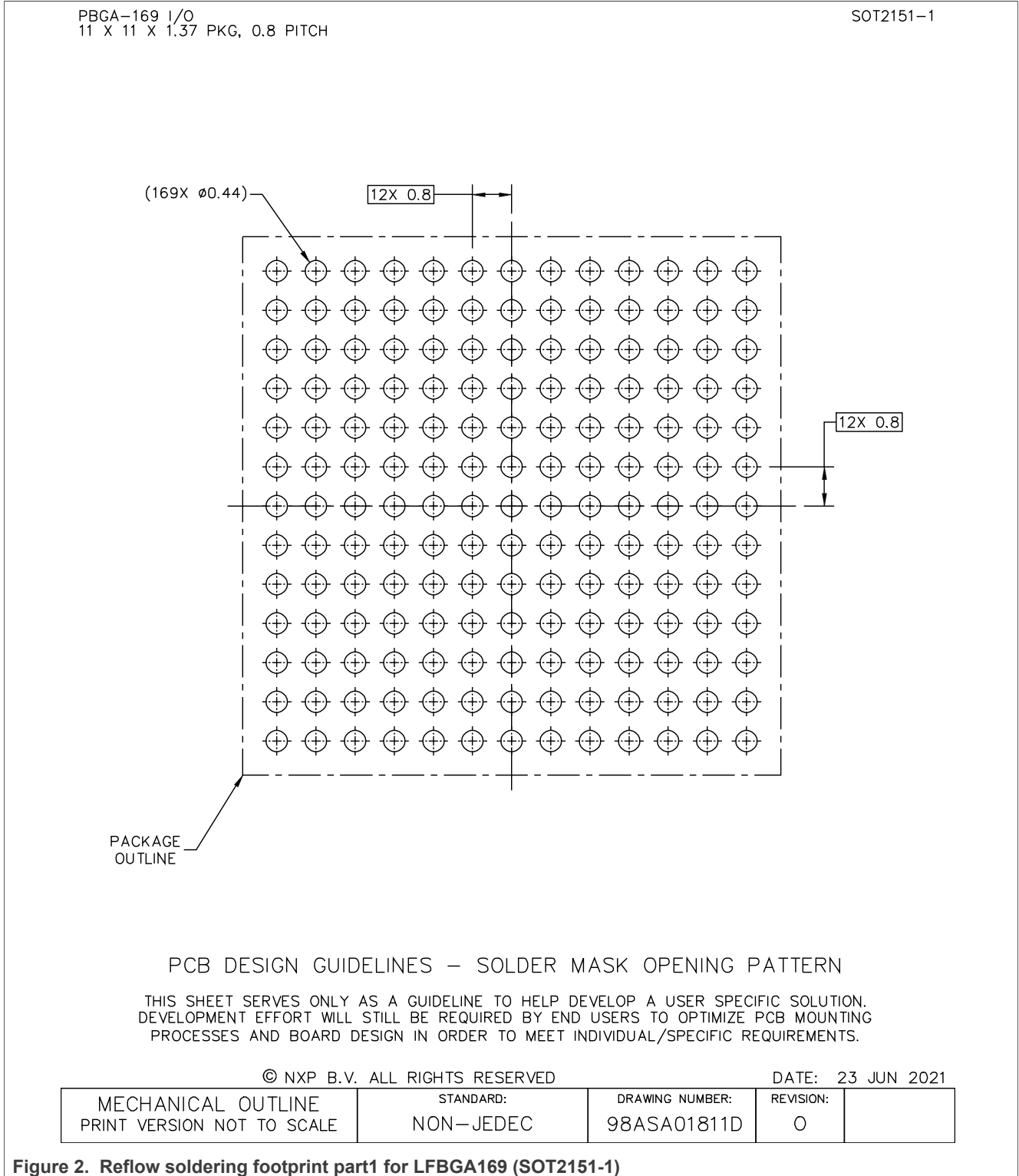
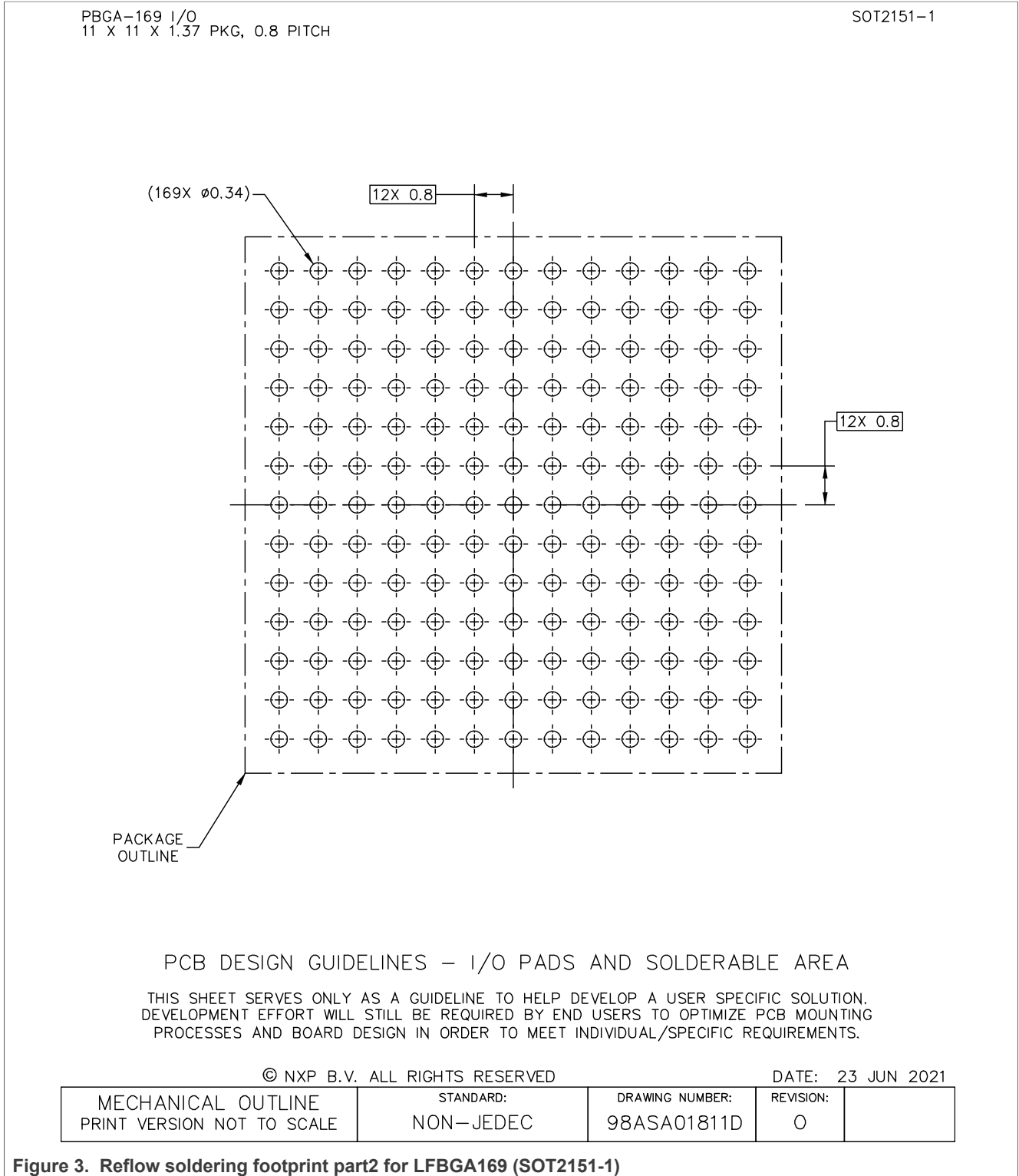


Figure 1. Package outline LFBGA169 (SOT2151-1)

3 Soldering



LFBGA169, low profile fine-pitch ball grid array package, 169 terminals, 0.8 mm pitch, 11 mm x 11 mm x 1.37 mm body



LFBGA169, low profile fine-pitch ball grid array package, 169 terminals, 0.8 mm pitch, 11 mm x 11 mm x 1.37 mm body

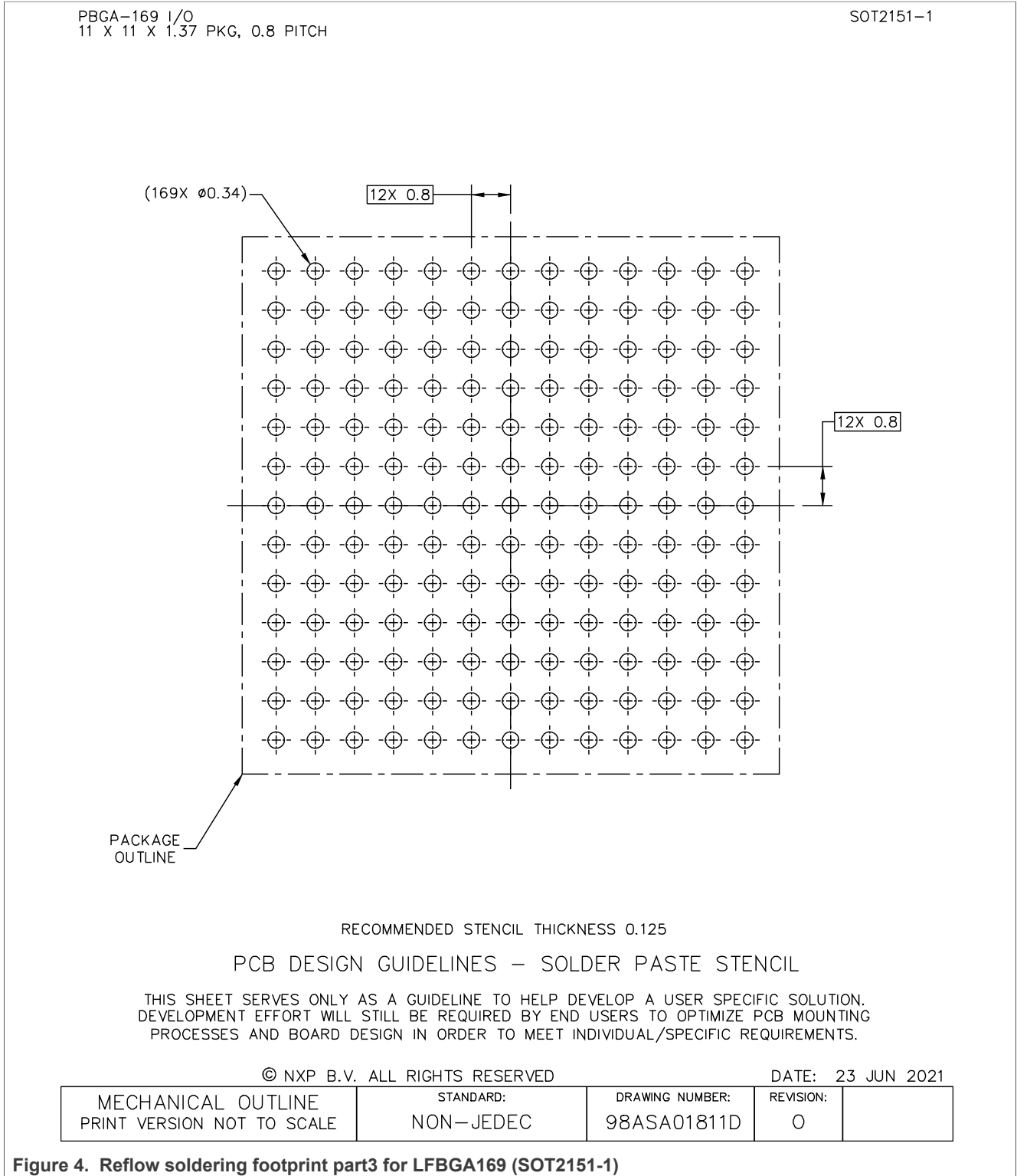


Figure 4. Reflow soldering footprint part3 for LFBGA169 (SOT2151-1)

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PBGA-169 I/O  
11 X 11 X 1.37 PKG, 0.8 PITCH

SOT2151-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 23 JUN 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01811D	REVISION: 0	
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Figure 5. Package outline note LFBGA169 (SOT2151-1)

## 4 Legal information

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